

Supporting Information

Enhanced Thermal Conductivity of Polymeric Composites

with BN@C Hybrid Fillers

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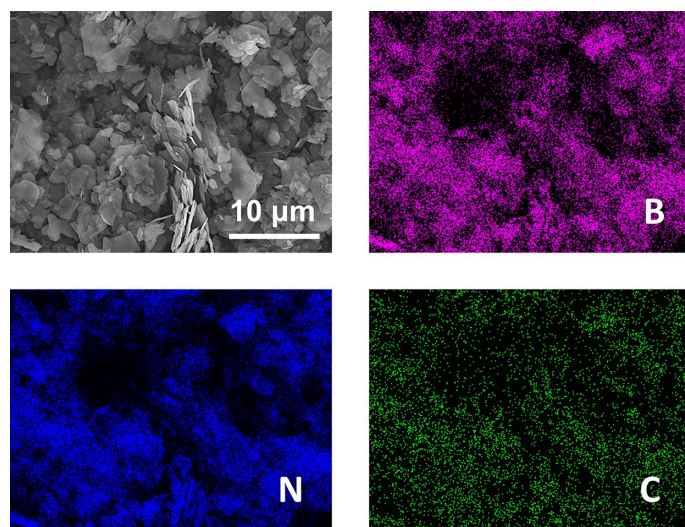


Fig. S1. EDS images of BN and BN@C2.

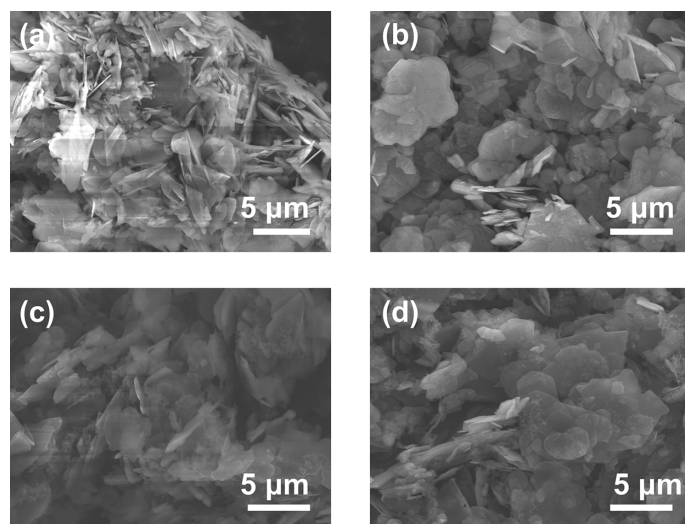


Fig. S2. SEM images of (a)BN, (b)BN@C2, (c)BN@C1, and (d)BN@C0.

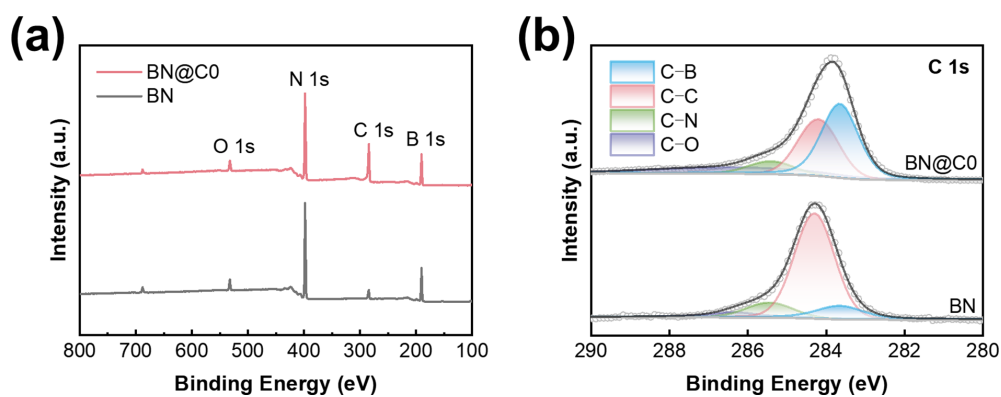


Fig. S3. (a) XPS spectra of BN@C0 and BN. (b) XPS C1s spectra of BN@C0 and BN.

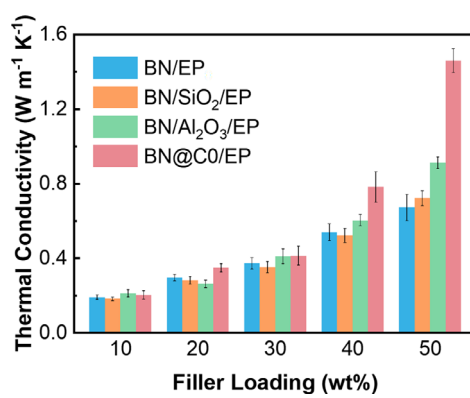


Fig. S4. Comparison of TC of composites constructed with different fillers.

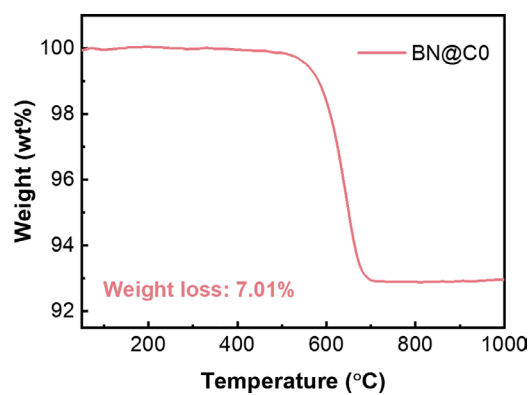


Fig. S5. TG of BN@C0 in air.

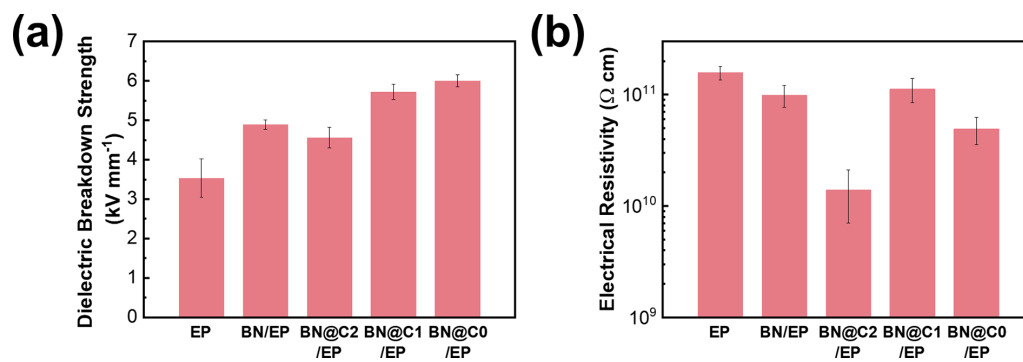


Fig. S6. (a) Dielectric breakdown strength. (b) Electrical resistivity.

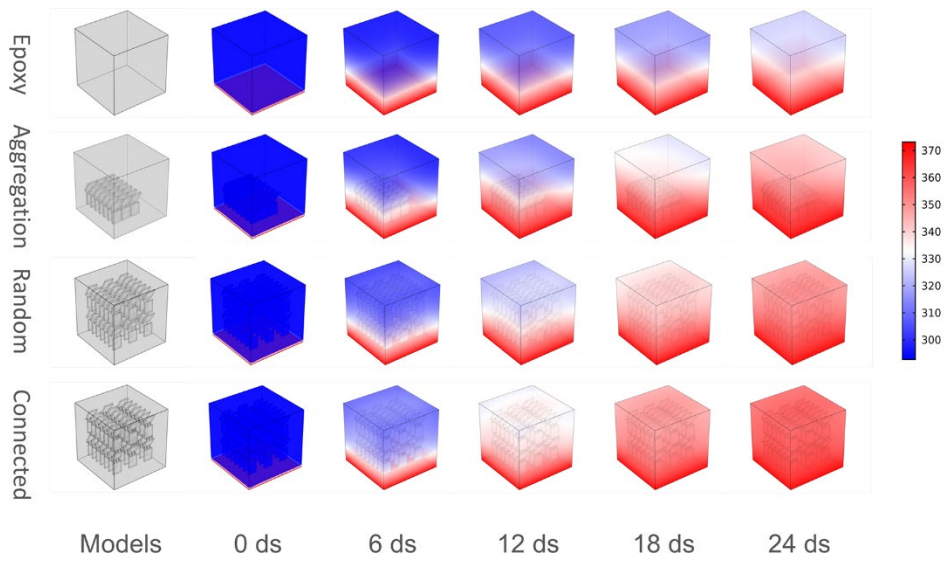


Fig. S7. Simulation of the thermal conduction process in composites.

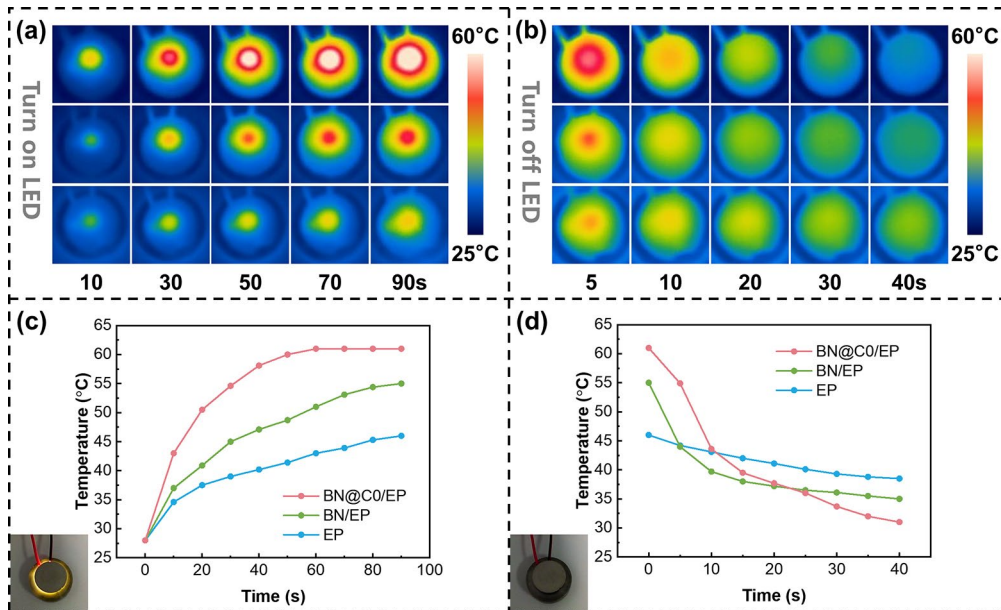


Fig. S8. Temperature distribution and variation in LED system for BN@C0/epoxy, BN/epoxy and epoxy.